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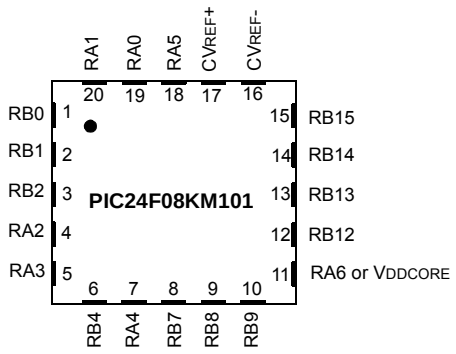
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b/12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08km202-i-ss

Pin Diagrams (Continued)

20-Pin QFN



Pin	Pin Features	
	PIC24F08KM101	PIC24FV08KM101
1	PGED1/AN2/CTCMP/ULPWU/C1IND/OC2A/CN4/RB0	
2	PGEC1/AN3/C1INC/CTED12/CN5/RB1	
3	AN4/U1RX/TCKIB/CTED13/CN6/RB2	
4	OSCI/CLKI/AN13/C1INB/CN30/RA2	
5	OSCO/CLKO/AN14/C1INA/CN29/RA3	
6	PGED3/SOSCI/AN15/CLCINA/CN1/RB4	
7	PGEC3/SOSCO/SCLKI/AN16/PWRLCLK/CLCINB/CN0/RA4	
8	AN19/U1TX/CTED1/INT0/CN23/RB7	AN19/U1TX/IC1/OC1A/CTED1/INT0/CN23/RB7
9	AN20/SCL1/$\overline{\text{U1CTS}}$/OC1B/CTED10/CN22/RB8	
10	AN21/SDA1/T1CK/$\overline{\text{U1RTS}}$/U1BCLK/IC2/CLC1O/CTED4/CN21/RB9	
11	IC1/OC1A/INT2/CN8/RA6	VCAP OR VDDCORE
12	AN12/HLVDIN/SCK1/OC1C/CTED2/CN14/RB12	AN12/HLVDIN/SCK1/OC1C/CTED2/INT2/CN14/RB12
13	AN11/SDO1/OCFB/OC1D/CTPLS/CN13/RB13	
14	CVREF/AN10/SDI1/C1OUT/OCFA/CTED5/INT1/CN12/RB14	
15	AN9/REFO/$\overline{\text{SS1}}$/TCKIA/CTED6/CN11/RB15	
16	VSS/AVSS	
17	VDD/AVDD	
18	$\overline{\text{MCLR}}$/VPP/RA5	
19	PGEC2/CVREF+ /VREF+/AN0/CN2/RA0	
20	PGED2/CVREF-/VREF-/AN1/CN3/RA1	

TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
RB9	13	18	15	1	1	13	18	15	1	1	I/O	ST	PORTB Pins
RB10	—	21	18	8	9	—	21	18	8	9	I/O	ST	PORTB Pins
RB11	—	22	19	9	10	—	22	19	9	10	I/O	ST	PORTB Pins
RB12	15	23	20	10	11	15	23	20	10	11	I/O	ST	PORTB Pins
RB13	16	24	21	11	12	16	24	21	11	12	I/O	ST	PORTB Pins
RB14	17	25	22	14	15	17	25	22	14	15	I/O	ST	PORTB Pins
RB15	18	26	23	15	16	18	26	23	15	16	I/O	ST	PORTB Pins
RC0	—	—	—	25	27	—	—	—	25	27	I/O	ST	PORTC Pins
RC1	—	—	—	26	28	—	—	—	26	28	I/O	ST	PORTC Pins
RC2	—	—	—	27	29	—	—	—	27	29	I/O	ST	PORTC Pins
RC3	—	—	—	36	39	—	—	—	36	39	I/O	ST	PORTC Pins
RC4	—	—	—	37	40	—	—	—	37	40	I/O	ST	PORTC Pins
RC5	—	—	—	38	41	—	—	—	38	41	I/O	ST	PORTC Pins
RC6	—	—	—	2	2	—	—	—	2	2	I/O	ST	PORTC Pins
RC7	—	—	—	3	3	—	—	—	3	3	I/O	ST	PORTC Pins
RC8	—	—	—	4	4	—	—	—	4	4	I/O	ST	PORTC Pins
RC9	—	—	—	5	5	—	—	—	5	5	I/O	ST	PORTC Pins
REFO	18	26	23	15	16	18	26	23	15	16	O	—	Reference Clock Output
RTCC	—	25	22	14	15	—	25	22	14	15	O	—	Real-Time Clock/Calendar Output
SCK1	15	22	19	9	10	15	22	19	9	10	I/O	ST	MSSP1 SPI Clock
SDI1	17	21	18	8	9	17	21	18	8	9	I	ST	MSSP1 SPI Data Input
SDO1	16	24	21	11	12	16	24	21	11	12	O	—	MSSP1 SPI Data Output
$\overline{SS1}$	18	26	23	15	16	18	26	23	15	16	I	ST	MSSP1 SPI Slave Select Input
SCK2	—	14	11	38	41	—	14	11	38	41	I/O	ST	MSSP2 SPI Clock
SDI2	—	19	16	36	39	—	19	16	36	39	I	ST	MSSP2 SPI Data Input
SDO2	—	15	12	37	40	—	15	12	37	40	O	—	MSSP2 SPI Data Output
$\overline{SS2}$	—	23	20	35	38	—	23	20	35	38	I	ST	MSSP2 SPI Slave Select Input

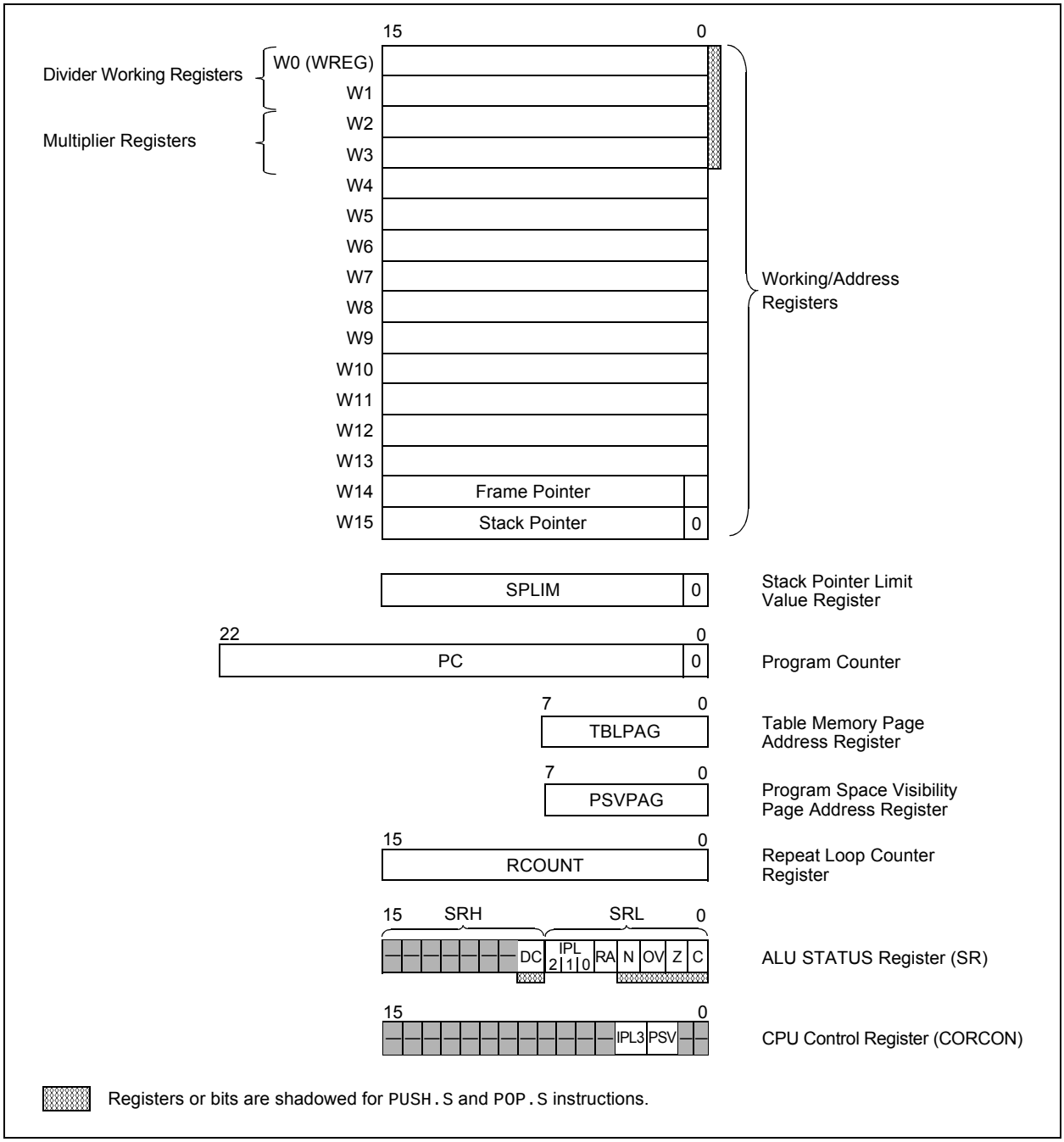
Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, I^2C™ = I^2C/SMBus input buffer

TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
SCL1	12	17	14	44	48	12	17	14	44	48	I/O	I2C	MSSP1 I^2C Clock
SDA1	13	18	15	1	1	13	18	15	1	1	I/O	I2C	MSSP1 I^2C Data
SCL2	—	7	4	24	26	—	7	4	24	26	I/O	I2C	MSSP2 I^2C Clock
SDA2	—	6	3	23	25	—	6	3	23	25	I/O	I2C	MSSP2 I^2C Data
SCLKI	10	12	9	34	37	10	12	9	34	37	I	ST	Secondary Clock Digital Input
SOSCI	9	11	8	33	36	9	11	8	33	36	I	ANA	Secondary Oscillator Input
SOSCO	10	12	9	34	37	10	12	9	34	37	I	ANA	Secondary Oscillator Output
T1CK	13	18	15	1	1	13	18	15	1	1	I	ST	Timer1 Digital Input Cock
TCKIA	18	26	23	15	16	18	26	23	15	16	I	ST	MCCP/SCCP Time Base Clock Input A
TCKIB	6	6	3	23	25	6	6	3	23	25	I	ST	MCCP/SCCP Time Base Clock Input B
$\overline{U1CTS}$	12	17	14	44	48	12	17	14	44	48	I	ST	UART1 Clear-To-Send Input
$\overline{U1RTS}$	13	18	15	1	1	13	18	15	1	1	O	—	UART1 Request-To-Send Output
U1BCLK	13	18	15	1	1	13	18	15	1	1	O	—	UART1 16x Baud Rate Clock Output
U1RX	6	6	3	2	2	6	6	3	2	2	I	ST	UART1 Receive
U1TX	11	16	13	3	3	11	16	13	3	3	O	—	UART1 Transmit
$\overline{U2CTS}$	—	12	9	34	37	—	12	9	34	37	I	ST	UART2 Clear-To-Send Input
$\overline{U2RTS}$	—	11	8	33	36	—	11	8	33	36	O	—	UART2 Request-To-Send Output
U2BCLK	13	18	15	1	1	13	18	15	1	1	O	—	UART2 16x Baud Rate Clock Output
U2RX	—	5	2	22	24	—	5	2	22	24	I	ST	UART2 Receive
U2TX	—	4	1	21	23	—	4	1	21	23	O	—	UART2 Transmit
ULPWU	4	4	1	21	23	4	4	1	21	23	I	ANA	Ultra Low-Power Wake-up Input
VCAP	—	—	—	—	—	14	20	17	7	7	P	—	Regulator External Filter Capacitor Connection
VDD	20	28	25	17,28,28	18,30,30	20	28	25	17,28,28	18,30,30	P	—	Device Positive Supply Voltage
VDDCORE	—	—	—	—	—	14	20	17	7	7	P	—	Microcontroller Core Supply Voltage
VPP	1	1	26	18	19	1	1	26	18	19	P	—	High-Voltage Programming Pin
VREF+	2	2	27	19	21	2	2	27	19	21	I	ANA	A/D Reference Voltage Positive Input
VREF-	3	3	28	20	22	3	3	28	20	22	I	ANA	A/D Reference Voltage Negative Input
VSS	19	27	24	16,29,29	17,31,31	19	27	24	16,29,29	17,31,31	P	—	Device Ground Return Voltage

Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, I^2C™ = I^2C/SMBus input buffer

FIGURE 3-2: PROGRAMMER'S MODEL



4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® devices and improve Data Space memory usage efficiency, the PIC24F instruction set supports both word and byte operations. As a consequence of byte accessibility, all EA calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word, which contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, the data memory and the registers are organized as two parallel, byte-wide entities with shared (word) address decode, but separate write lines. Data byte writes only write to the corresponding side of the array or register, which matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap will be generated. If the error occurred on a read, the instruction underway is completed; if it occurred on a write, the instruction will be executed, but the write will not occur. In either case, a trap is then executed, allowing the system and/or user to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB; the MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow the users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

Although most instructions are capable of operating on word or byte data sizes, it should be noted that some instructions operate only on words.

4.2.3 NEAR DATA SPACE

The 8-Kbyte area between 0000h and 1FFFh is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. The remainder of the Data Space is addressable indirectly. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing (MDA) with a 16-bit address field. For PIC24FV16KM204 family devices, the entire implemented data memory lies in Near Data Space (NDS).

4.2.4 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0000h to 07FFh, are primarily occupied with Special Function Registers (SFRs). These are used by the PIC24F core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by that module. Much of the SFR space contains unused addresses; these are read as '0'. The SFR space, where the SFRs are actually implemented, is provided in Table 4-2. Each implemented area indicates a 32-byte region where at least one address is implemented as an SFR. A complete listing of implemented SFRs, including their addresses, is provided in Table 4-3 through Table 4-26.

TABLE 4-2: IMPLEMENTED REGIONS OF SFR DATA SPACE

	SFR Space Address							
	xx00	**xx20**	**xx40**	**xx60**	**xx80**	**xxA0**	**xxC0**	**xxE0**
000h	Core			ICN	Interrupts			—
100h	Timers	CLC	MCCP/SCCP					
200h	MSSP	UART	Op Amp	DAC	—	—	I/O	
300h	A/D/CMTU				—	—	—	—
400h	—	—	—	—	—	—	—	ANSEL
500h	—	—	—	—	—	—	—	—
600h	—	RTCC/Comp	—	Band Gap	—			
700h	—	—	System/ HLVD	NVM/PMD	—	—	—	—

Legend: — = No implemented SFRs in this block.

TABLE 4-13: MSSP1 (I^2C™/SPI) REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SSP1BUF	200h	—	—	—	—	—	—	—	—	MSSP1 Receive Buffer/Transmit Register								00xx
SSP1CON1	202h	—	—	—	—	—	—	—	—	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000
SSP1CON2	204h	—	—	—	—	—	—	—	—	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000
SSP1CON3	206h	—	—	—	—	—	—	—	—	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000
SSP1STAT	208h	—	—	—	—	—	—	—	—	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000
SSP1ADD	20Ah	—	—	—	—	—	—	—	—	MSSP1 Address Register in I^2C Slave Mode MSSP1 Baud Rate Reload Register in I^2C Master Mode								0000
SSP1MSK	20Ch	—	—	—	—	—	—	—	—	MSK7	MSK6	MSK5	MSK4	MSK3	MSK2	MSK1	MSK0	00FF

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.

TABLE 4-14: MSSP2 (I^2C™/SPI) REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SSP2BUF(1)	210h	—	—	—	—	—	—	—	—	MSSP2 Receive Buffer/Transmit Register								00xx
SSP2CON1(1)	212h	—	—	—	—	—	—	—	—	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000
SSP2CON2(1)	214h	—	—	—	—	—	—	—	—	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000
SSP2CON3(1)	216h	—	—	—	—	—	—	—	—	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000
SSP2STAT(1)	218h	—	—	—	—	—	—	—	—	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000
SSP2ADD(1)	21Ah	—	—	—	—	—	—	—	—	MSSP2 Address Register in I^2C Slave Mode MSSP2 Baud Rate Reload Register in I^2C Master Mode								0000
SSP2MSK(1)	21Ch	—	—	—	—	—	—	—	—	MSK7	MSK6	MSK5	MSK4	MSK3	MSK2	MSK1	MSK0	00FF

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.

Note 1: These registers are available only on PIC24F(V)16KM2XX devices.

4.3.2 DATA ACCESS FROM PROGRAM MEMORY AND DATA EEPROM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program memory without going through Data Space. It also offers a direct method of reading or writing a word of any address within data EEPROM memory. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

Note: The TBLRDH and TBLWTH instructions are not used while accessing data EEPROM memory.

The PC is incremented by 2 for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit, word-wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word, and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.

2. TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom' byte, will always be '0'.

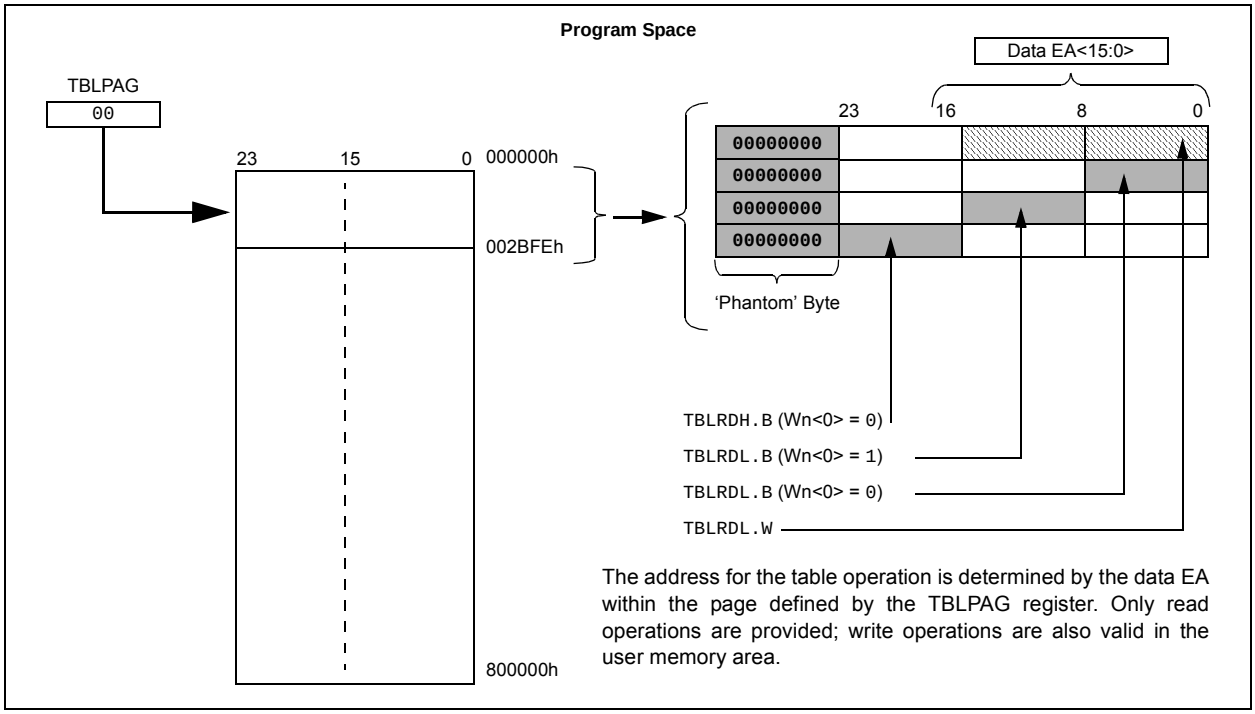
   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Memory Page Address register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

Note: Only Table Read operations will execute in the configuration memory space, and only then, in implemented areas, such as the Device ID. Table Write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



The address for the table operation is determined by the data EA within the page defined by the TBLPAG register. Only read operations are provided; write operations are also valid in the user memory area.

REGISTER 8-22: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	NVMIP2	NVMIP1	NVMIP0	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	AD1IP2	AD1IP1	AD1IP0	—	U1TXIP2	U1TXIP1	U1TXIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **NVMIP<2:0>:** NVM Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11-7 **Unimplemented:** Read as ‘0’

bit 6-4 **AD1IP<2:0>:** A/D Conversion Complete Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **U1TXIP<2:0>:** UART1 Transmitter Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

10.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Power-Saving Features with VBAT"** (DS30622).

This FRM describes some features which are not implemented in this device. Sections related to the VBAT pin and Deep Sleep do not apply to the PIC24FV16KM204 family.

The PIC24FV16KM204 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation.

The 'C' syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode includes these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption will be reduced to a minimum provided that no I/O pin is sourcing current.
- The I/O pin directions and states are frozen.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock will continue to run in Sleep mode if the WDT or RTCC with LPRC as the clock source is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items, such as the Input Change Notification on the I/O ports or peripherals that use an External Clock input. Any peripheral that requires the system clock source for its operation will be disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- On any interrupt source that is individually enabled
- On any form of device Reset
- On a WDT time-out

On wake-up from Sleep, the processor will restart with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: 'C' POWER-SAVING ENTRY

```
Sleep();              //Put the device into Sleep mode
Idle();               //Put the device into Idle mode
```

13.4 Input Capture Mode

Input Capture mode is used to capture a timer value from an independent timer base upon an event on an input pin or other internal Trigger source. The input capture features are useful in applications requiring frequency (time period) and pulse measurement. Figure 13-6 depicts a simplified block diagram of Input Capture mode.

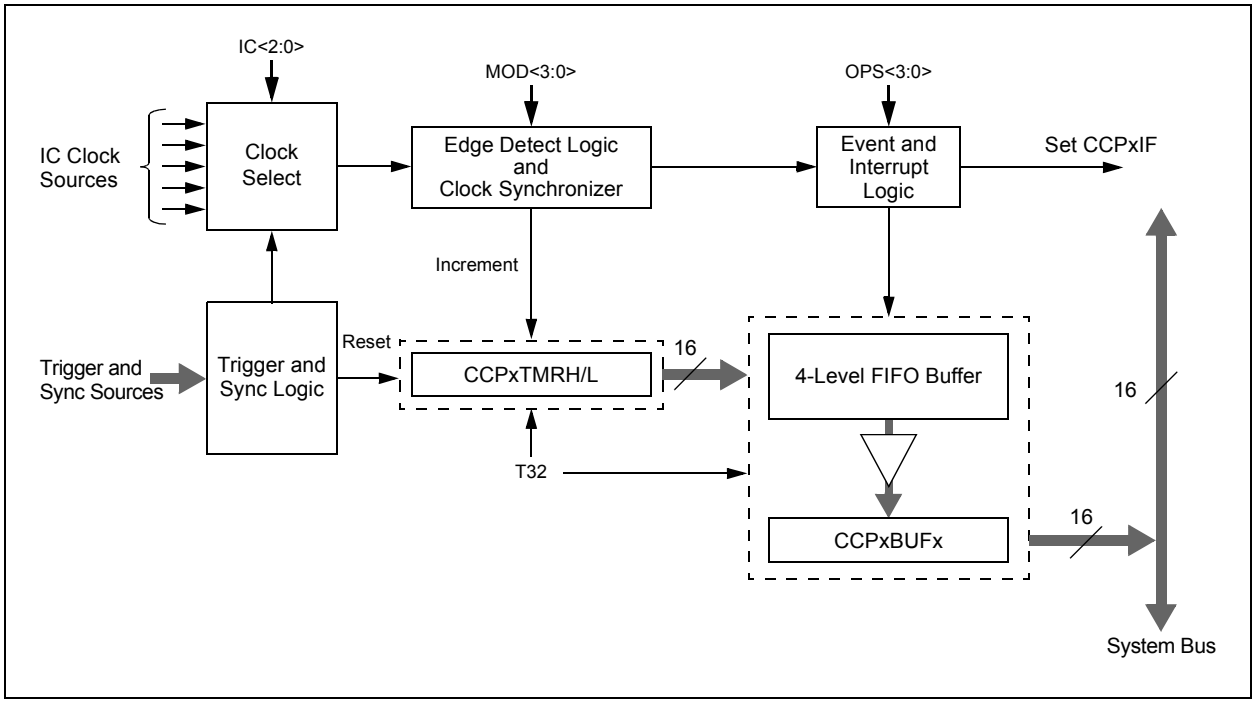
Input Capture mode uses a dedicated 16/32-bit, synchronous, up counting timer for the capture function. The timer value is written to the FIFO when a capture event occurs. The internal value may be read (with a synchronization delay) using the CCPxTMRH/L register.

To use Input Capture mode, the CCSEL bit (CCPxCON1L<4>) must be set. The T32 and the MOD<3:0> bits are used to select the proper Capture mode, as shown in Table 13-4.

TABLE 13-4: INPUT CAPTURE MODES

MOD<3:0> (CCPxCON1L<3:0>)	T32 (CCPxCON1L<5>)	Operating Mode
0000	0	Edge Detect (16-bit capture)
0000	1	Edge Detect (32-bit capture)
0001	0	Every Rising (16-bit capture)
0001	1	Every Rising (32-bit capture)
0010	0	Every Falling (16-bit capture)
0010	1	Every Falling (32-bit capture)
0011	0	Every Rise/Fall (16-bit capture)
0011	1	Every Rise/Fall (32-bit capture)
0100	0	Every 4th Rising (16-bit capture)
0100	1	Every 4th Rising (32-bit capture)
0101	0	Every 16th Rising (16-bit capture)
0101	1	Every 16th Rising (32-bit capture)

FIGURE 13-6: INPUT CAPTURE x BLOCK DIAGRAM



REGISTER 15-3: UxTXREG: UARTx TRANSMIT REGISTER

U-x	U-x	U-x	U-x	U-x	U-x	U-x	W-x
—	—	—	—	—	—	—	UTX8
bit 15							bit 8

W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
UTX7	UTX6	UTX5	UTX4	UTX3	UTX2	UTX1	UTX0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **UTX8:** Data of the Transmitted Character bit (in 9-bit mode)

bit 7-0 **UTX<7:0>:** Data of the Transmitted Character bits

REGISTER 15-4: UxRXREG: UARTx RECEIVE REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC
—	—	—	—	—	—	—	URX8
bit 15							bit 8

R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
URX7	URX6	URX5	URX4	URX3	URX2	URX1	URX0
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **URX8:** Data of the Received Character bit (in 9-bit mode)

bit 7-0 **URX<7:0>:** Data of the Received Character bits

REGISTER 17-5: CLCxGLSH: CLCx GATE LOGIC INPUT SELECT HIGH REGISTER (CONTINUED)

bit 3 **G3D2T:** Gate 3 Data Source 2 True Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 3
0 = The Data Source 2 inverted signal is disabled for Gate 3

bit 2 **G3D2N:** Gate 3 Data Source 2 Negated Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 3
0 = The Data Source 2 inverted signal is disabled for Gate 3

bit 1 **G3D1T:** Gate 3 Data Source 1 True Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 3
0 = The Data Source 1 inverted signal is disabled for Gate 3

bit 0 **G3D1N:** Gate 3 Data Source 1 Negated Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 3
0 = The Data Source 1 inverted signal is disabled for Gate 3

REGISTER 19-3: AD1CON3: A/D CONTROL REGISTER 3

R/W-0	R-0	r-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	EXTSAM	r	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS7	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** A/D Conversion Clock Source bit
1 = RC clock
0 = Clock is derived from the system clock

bit 14 **EXTSAM:** Extended Sampling Time bit
1 = A/D is still sampling after SAMP = 0
0 = A/D is finished sampling

bit 13 **Reserved:** Maintain as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time Select bits
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** A/D Conversion Clock Select bits
11111111-01000000 = Reserved
00111111 = 64 * TCY = TAD
•
•
•
00000001 = 2 * TCY = TAD
00000000 = TCY = TAD

REGISTER 19-5: AD1CHS: A/D SAMPLE SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB2	CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **CH0NB<2:0>:** Sample B Channel 0 Negative Input Select bits
111 = AN6(1)
110 = AN5(2)
101 = AN4
100 = AN3
011 = AN2
010 = AN1
001 = AN0
000 = AVSS

bit 12-8 **CH0SB<4:0>:** S/H Amplifier Positive Input Select for MUX B Multiplexer Setting bits
11111 = Unimplemented, do not use
11110 = AVDD(3)
11101 = AVSS(3)
11100 = Upper guardband rail (0.785 * VDD)
11011 = Lower guardband rail (0.215 * VDD)
11010 = Internal Band Gap Reference (VBG)(3)
11000-11001 = Unimplemented, do not use
10001 = No channels are connected, all inputs are floating (used for CTMU)
10111 = No channels are connected, all inputs are floating (used for CTMU)
10110 = No channels are connected, all inputs are floating (used for CTMU temperature sensor input); does not require the corresponding CTMEN22 (AD1CTMENH<6>) bit)
10101 = Channel 0 positive input is AN21
10100 = Channel 0 positive input is AN20
10011 = Channel 0 positive input is AN19
10010 = Channel 0 positive input is AN18(2)
10001 = Channel 0 positive input is AN17(2)
•
•
•
01001 = Channel 0 positive input is AN9
01000 = Channel 0 positive input is AN8(1)
00111 = Channel 0 positive input is AN7(1)
00110 = Channel 0 positive input is AN6(1)
00101 = Channel 0 positive input is AN5(2)
00100 = Channel 0 positive input is AN4
00011 = Channel 0 positive input is AN3
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

Note 1: This is implemented on 44-pin devices only.
2: This is implemented on 28-pin and 44-pin devices only.
3: The band gap value used for this input is 2x or 4x the internal VBG, which is selected when PVCFG<1:0> = 1x.

REGISTER 20-1: DACxCON: DACx CONTROL REGISTER (CONTINUED)

bit 6-2 **DACTSEL<4:0>:** DACx Trigger Source Select bits
11101-11111 = Unused
11100 = CTMU
11011 = A/D
11010 = Comparator 3
11001 = Comparator 2
11000 = Comparator 1
10011 to 10111 = Unused
10010 = CLC2 output
10001 = CLC1 output
01100 to 10000 = Unused
01011 = Timer1 Sync output
01010 = External Interrupt 2
01001 = External Interrupt 1
01000 = External Interrupt 0
0011x = Unused
00101 = MCCP5 or SCCP5 Sync output
00100 = MCCP4 or SCCP4 Sync output
00011 = MCCP3 or SCCP3 Sync output
00010 = MCCP2 or SCCP2 Sync output
00001 = MCCP1 or SCCP1 Sync output
00000 = Unused

bit 1-0 **DACREF<1:0>:** DACx Reference Source Select bits
11 = Internal Band Gap Buffer 1 (BGBUF1)**(1)**
10 = AV_{DD}
01 = DV_{REF+}
00 = Reference is not connected (lowest power but no DAC functionality)

Note 1: BGBUF1 voltage is configured by BUFREF<1:0> (BUFCON0<1:0>).

22.0 COMPARATOR MODULE

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Comparator module, refer to the *"PIC24F Family Reference Manual"*, **"Scalable Comparator Module"** (DS39734).

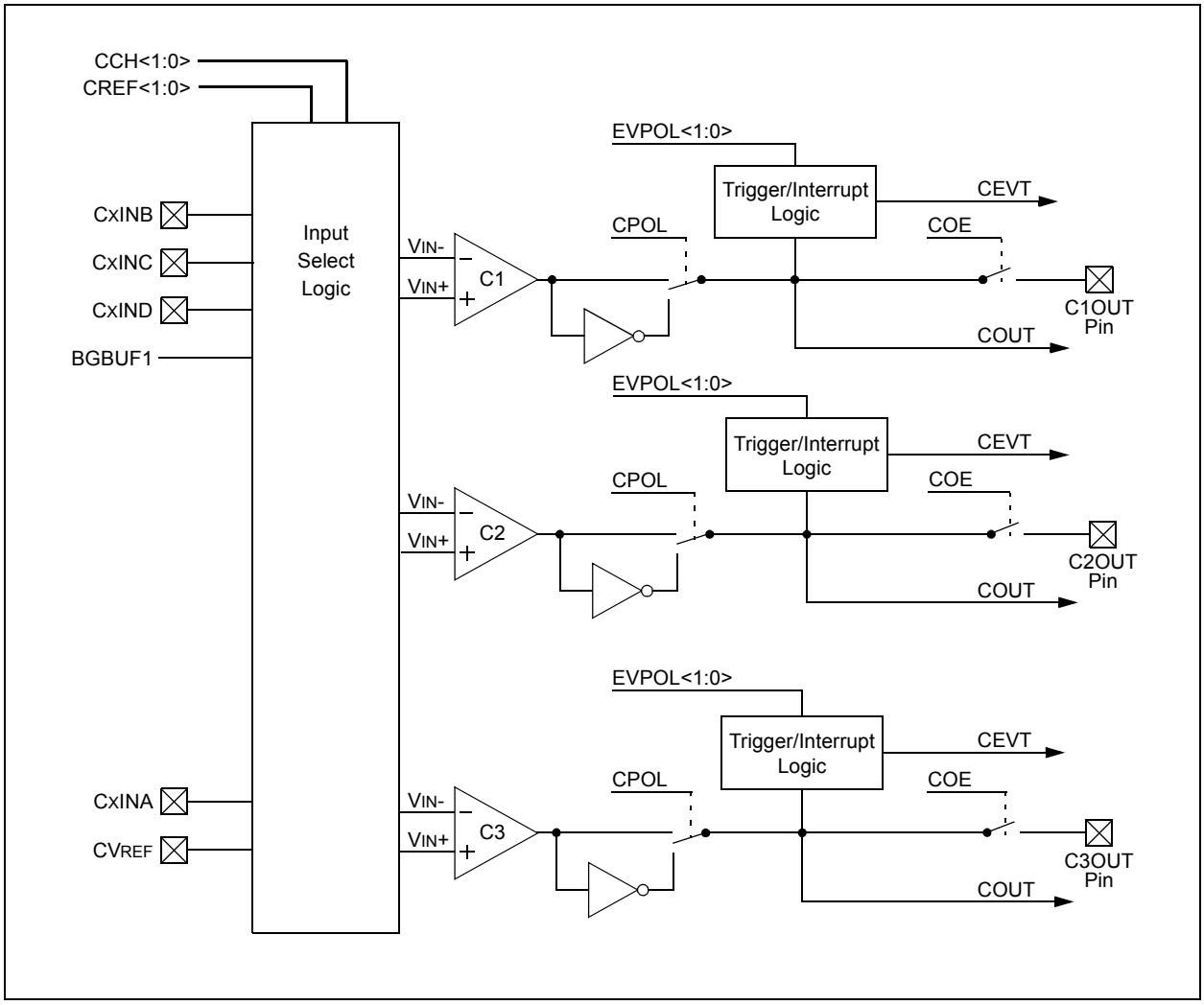
The comparator module provides three dual input comparators. The inputs to the comparator can be configured to use any one of four external analog inputs, as well as a voltage reference input from either the Internal Band Gap Buffer 1 (BGBUF1) or the comparator voltage reference generator.

The comparator outputs may be directly connected to the CxOUT pins. When the respective COE bit equals '1', the I/O pad logic makes the unsynchronized output of the comparator available on the pin.

A simplified block diagram of the module is shown in Figure 22-1. Diagrams of the possible individual comparator configurations are shown in Figure 22-2.

Each comparator has its own control register, CMxCON (Register 22-1), for enabling and configuring its operation. The output and event status of all three comparators is provided in the CMSTAT register (Register 22-2).

FIGURE 22-1: COMPARATOR x MODULE BLOCK DIAGRAM



REGISTER 24-1: CTMUCON1L: CTMU CONTROL 1 LOW REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** CTMU Trigger Control bit
1 = Trigger output is enabled
0 = Trigger output is disabled

bit 7-2 **ITRIM<5:0>:** Current Source Trim bits
011111 = Maximum positive change from nominal current
011110
•
•
•
000001 = Minimum positive change from nominal current
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current
•
•
•
100010
100001 = Maximum negative change from nominal current

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

If the WDT is enabled in hardware (FWDTEN<1:0> = 11), it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3:2>) will need to be cleared in software after the device wakes up.

The WDT Flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

Note:	The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

25.3.1 WINDOWED OPERATION

The Watchdog Timer has an optional Fixed Window mode of operation. In this Windowed mode, CLRWDT instructions can only reset the WDT during the last 1/4 of the programmed WDT period. A CLRWDT instruction executed before that window causes a WDT Reset, similar to a WDT time-out.

Windowed WDT mode is enabled by programming the Configuration bit, WINDIS (FWDT<6>), to '0'.

25.3.2 CONTROL REGISTER

The WDT is enabled or disabled by the FWDTEN<1:0> Configuration bits. When both of the FWDTEN<1:0> Configuration bits are set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN<1:0> Configuration bits have been programmed to '10'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments, and disable the WDT during non-critical segments, for maximum power savings. When the FWDTEN<1:0> bits are set to '01', the WDT is only enabled in Run and Idle modes, and is disabled in Sleep. Software control of the SWDTEN bit (RCON<5>) is disabled with this setting.

FIGURE 25-2: WDT BLOCK DIAGRAM

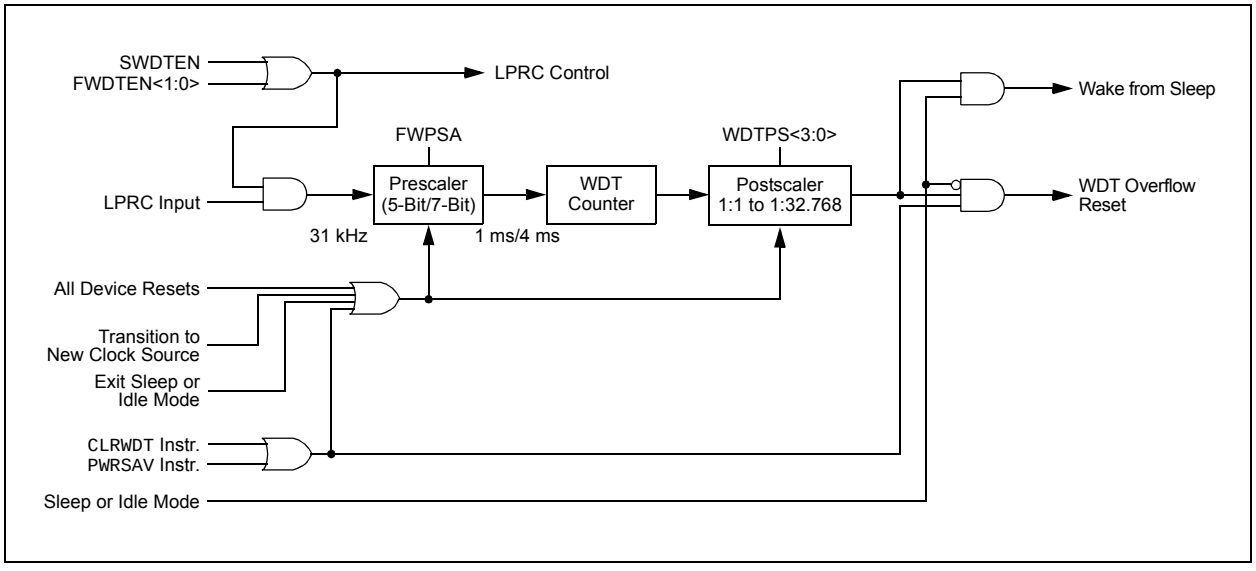


TABLE 27-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Operating Conditions: -40°C < TA < +85°C (unless otherwise stated) -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
	VBG	Band Gap Reference Voltage	0.973	1.024	1.075	V	VDD > 4.5V for 4*VBG reference VDD > 2.3V for 2*VBG reference
	TBG	Band Gap Reference Start-up Time	—	1	—	ms	
	VRGOUT	Regulator Output Voltage	3.1	3.3	3.6	V	
	CEFC	External Filter Capacitor Value	4.7	10	—	μF	Series resistance < 3 Ohm recommended; < 5 Ohm is required.
	VLVR	Low-Voltage Regulator Output Voltage	—	2.6	—	V	

TABLE 27-16: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204)** **2.0V to 5.5V (PIC24FV16KM204)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Comments**	**Conditions**
	IOUT1	CTMU Current Source, Base Range	—	550	—	nA	CTMUCON1L<1:0> = 01	2.5V < VDD < VDDMAX
	IOUT2	CTMU Current Source, 10x Range	—	5.5	—	μA	CTMUCON1L<1:0> = 10	
	IOUT3	CTMU Current Source, 100x Range	—	55	—	μA	CTMUCON1L<1:0> = 11	
	IOUT4	CTMU Current Source, 1000x Range	—	550	—	μA	CTMUCON1L<1:0> = 00 **(Note 2)**	
	VF	Temperature Diode Forward Voltage	—	.76	—	V		
	VΔ	Voltage Change per Degree Celsius	—	1.6	—	mV/°C		

Note 1: Nominal value at the center point of the current trim range (CTMUCON1L<7:2> = 000000). On PIC24F16KM parts, the current output is limited to the typical current value when IOUT4 is chosen.

2: Do not use this current range with a temperature sensing diode.

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- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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